

POWER DISSIPATION (SON1408-3)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

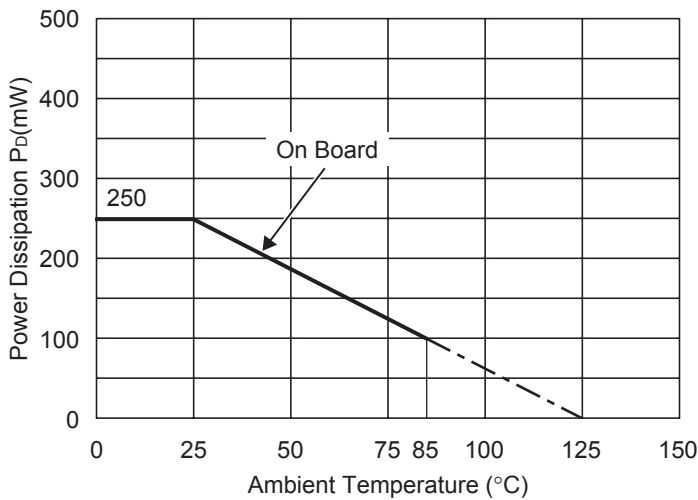
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plactic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.8mm × 24pcs

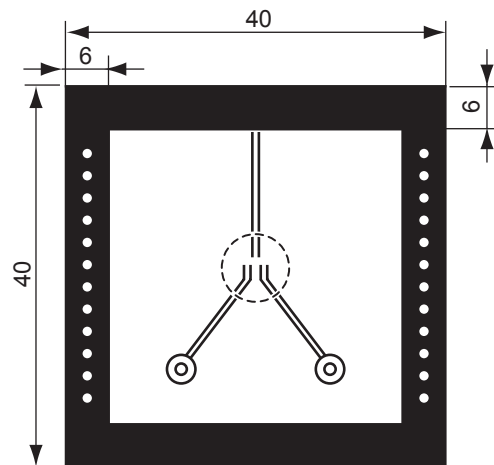
Measurement Result

($T_{opt}=25^{\circ}C, T_{jmax}=125^{\circ}C$)

	Standard Land Pattern
Power Dissipation	250mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/0.25W=400^{\circ}C/W$



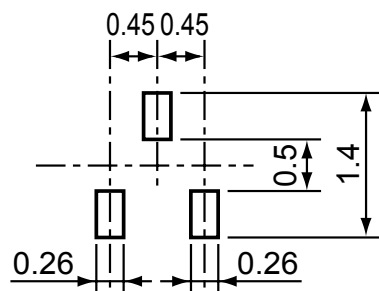
Power Dissipation



Measurement Board Pattern

○ IC Mount Area (Unit : mm)

RECOMMENDED LAND PATTERN (SON1408-3)



(Unit : mm)